



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Sectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-05-10
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Floriana SAN BIAGIO	Representative Title	AMS MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	8R72*U1C5BB5	A	CA2A	2018-05-10
Amount	UoM	Unit type	ST ECOPACK Grade	
29.80	mg	Each	ECOPACK® 2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
QFN	3x3x1	16	flat	
Comment	72 VFQFPN 16 3x3x1.0 PITCH 0.50; MDF valdi for L6739TR			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	8R72*U1C5885					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other Inorganic materials	1.208	mg	supplier	die	Silicon (Si)	7440-21-3		1.134	mg	938742	38054
				supplier	metallization	Aluminium (Al)	7429-90-5		0.012	mg	9934	403
				supplier	metallization	Tungsten (W)	7440-33-7		0.009	mg	7450	302
				supplier	Passivation	Silicon Nitride	12033-89-5		0.002	mg	1656	67
				supplier	Passivation	Silicon Oxide	7631-86-9		0.020	mg	16556	671
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.001	mg	828	34
				supplier	back side metallization	Gold (Au)	7440-57-5		0.002	mg	1656	67
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.008	mg	6623	268
				supplier	polymer die coating	PIXI Polyimide	108-65-6		0.008	mg	6623	268
				supplier	polymer die coating	PIXI Gamma-butyrolactone	96-48-0		0.012	mg	9934	403
				Leadframe	Copper & its alloys	12.187	mg	supplier	alloy	Copper (Cu)	7440-50-8	
supplier	alloy	Nickel (Ni)	7440-02-0						0.363	mg	29786	12181
supplier	alloy	Magnesium (Mg)	7439-95-4						0.018	mg	1477	604
supplier	alloy	Silicon (Si)	7440-21-3						0.079	mg	6482	2651
supplier	metallization	Nickel (Ni)	7440-02-0						0.074	mg	6072	2483
supplier	metallization	Palladium (Pd)	7440-05-3						0.005	mg	410	168
supplier	metallization	Gold (Au)	7440-57-5						0.002	mg	164	67
supplier	glue	Silver (Ag)	7440-22-4						0.341	mg	800469	11443
Die attach	Other Organic Materials	0.426	mg	supplier	glue	methylenediacylate	42594-17-2		0.057	mg	133803	1913
				supplier	glue	Dicyclopentenyloxyethyl methacrylate	68586-19-6		0.011	mg	25822	369
				supplier	glue	Polybutadiene Anhydride	Proprietary		0.013	mg	30516	436
				supplier	glue	Epoxycyclohexylethyltrimethoxysilane	3388-04-3		0.002	mg	4695	67
				supplier	glue	Bis(α,α -dimethylbenzyl) peroxide	80-43-3		0.002	mg	4695	67
				supplier	wire	Gold (Au)	7440-57-5		0.184	mg	989247	6174
Bonding wires	Precious metals	0.186	mg	supplier	wire	Palladium (Pd)	7440-05-3		0.002	mg	10753	67
				supplier	silica vitreous	silica vitreous	60676-86-0		13.474	mg	852947	452148
				supplier	mold compound	epoxy resin	29690-82-2		0.632	mg	40008	21208
				supplier	mold compound	Phenol resin	25068-38-6		0.553	mg	35007	18557
				supplier	mold compound	Magnesium hydroxide	1309-42-8		0.632	mg	40008	21208
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		0.316	mg	20004	10604
				supplier	mold compound	Zinc hydroxide	20427-58-1		0.158	mg	10002	5302
				supplier	mold compound	carbon black	1333-86-4		0.032	mg	2026	1074
Encapsulation	Other Organic Materials	15.797	mg	supplier	mold compound	silica vitreous	60676-86-0		13.474	mg	852947	452148
				supplier	mold compound	epoxy resin	29690-82-2		0.632	mg	40008	21208
				supplier	mold compound	Phenol resin	25068-38-6		0.553	mg	35007	18557
				supplier	mold compound	Magnesium hydroxide	1309-42-8		0.632	mg	40008	21208
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		0.316	mg	20004	10604
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